

CKC33C622MEGAC7210

KC-LINK Comm COG, Ceramic, 6200 pF, 20%, 1200 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640



Click here for the 3D model.

Dimensions	
Chip Size	3640
L	9.3mm +/-0.6mm
W	10.2mm +/-0.4mm
T	1.4mm +/-0.15mm
В	1.27mm +/-0.4mm

Packaging Specifications		
Packaging	T&R, 330mm, Plastic Tape	
Packaging Quantity	1000	

General Information		
Series	KC-LINK Comm COG	
Style	SMD Chip	
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I	
Features	Ultra-Stable, Low Loss, Class I	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Component Weight	18 mg	
Shelf Life	78 Weeks	
MSL	1	

Specifications	
Capacitance	6200 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	1200 VDC
Dielectric Withstanding Voltage	1440 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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